SMART ELECTRONICS

Specification _ Smart Electronics Flex Board Capabilities

Parametre		Standard	Advance
Maximum board size		100 x 140 mm	480 x 380 mm
Maximum Board Thickness	1 (copper) layer	0.15 mm	0.6 mm
	2 layers	0.16 mm	0.12mm
	4 layers	0.4mm	0.2mm
Minimum Board Thickness	1 (copper) layer	0.1 mm	0.05mm
	2 layers	0.12 mm	0.1mm
	4 layers	0.3 mm	0.25mm
Maximum Number of Layers		4 layers	6 layers
Minimum PTH (Plated Thru Hole) diameter		0.2 mm	0.1mm
Minimum Traces/Spaces		0.75 mm / 0.75 mm	0.5 mm / 0.5 mm
Copper		One-sided or double-sided	
Surface		OSP , ENIG , Quartz plating	Palladium gold plating , Electrolysis soft gold plating
Foil material		Polyimide	
Polyimide thickness		18 µm	50 µm
Copper thickness		18 µm	35 µm
Minimum conductor width / conductor distance		25 µm	50 µm
Vias		Via diameter: 100 µm	Via diameter: 85 µm
Milling tolerance		75 µm	50 µm

Drill Hole to Copper Features

Outer Layer	0.15	0.1
Inner Layer - Signal	0.15	0.1
Inner Layer - Plane	0.15	0.1
Drill Via Size		
Flex	0.15	0.1
Rigid-Flex .040	0.2	0.15
Rigid-Flex .062	0.2	0.15
Rigid-Flex .093	0.2	0.15
Blind laser Via's	0.13	0.1
Annular Ring		
Print and Plate	0.1	0.05
Pads Plate	0.1	0.05
Laser Via Capture Pads	0.1	0.05
Trace Width		
1 oz (0.0014)	0.1	0.075
1/2 oz (0.0007)	0.075	0.05
Spacing		
1 oz (0.0014)	0.1	0.075
1/2 oz (0.0007)	0.075	0.05
Misc.		
Silkscreen Line Width	0.1	0.08
Copper to Board Edge		
Hole Size Tolerance	0.05	0.05
Coverlay Opening	0.1	0.075
Coverlay Web (Kapton)	0.3	0.2
Layer Count	6	1000
Core Thickness (Rigid)	0.1	0.1
Core Thickness (Flex)	0.05	0.012